

Merit



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*This certificate is granted and awarded by the authority of the Nadcap Management Council to:*

## ***ADI - Electronics Manufacturing Technologies Pvt Ltd***

*Sy No 10/1A Whitefield Road, Hoody K.R. Puram Hobli  
Bangalore, KA 560048  
India*

*This certificate demonstrates conformance and recognition of accreditation for specific services, as listed in [www.eAuditNet.com](http://www.eAuditNet.com) on the Qualified Manufacturer's List (QML), to the revision in effect at the time of the audit for:*

## ***Electronics - Printed Board Assemblies***

Certificate Number: 17886229399  
Expiration Date: 31 August 2027  
Accreditation Length: 24 Months

**Jay Solomond**  
Executive Vice President & Chief Operating Officer

Merit

Performance Review Institute (PRI) | 161 Thorn Hill Road | Warrendale, PA 15086-7527

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## SCOPE OF ACCREDITATION

### Electronics - Printed Board Assemblies

**ADI - Electronics Manufacturing Technologies Pvt Ltd**  
Sy No 10/1A Whitefield Road, Hoody K.R. Puram Hobli  
Bangalore, KA 560048  
India

This certificate expiration is updated based on periodic audits. The current expiration date and scope of accreditation are listed at: [www.eAuditNet.com](http://www.eAuditNet.com) - Online QML (Qualified Manufacturer Listing).

In recognition of the successful completion of the PRI evaluation process, accreditation is granted to this facility to perform the following:

#### **AC7000 Rev A - AUDIT CRITERIA FOR NADCAP ACCREDITATION**

##### **AC7120 Rev E - Nadcap Audit Criteria for Printed Board Assemblies (to be used on audits on/after 9 April 2017) (CANNOT BE COMBINED WITH AC7119 or AC7121)**

In-Process Verification / Inspection: AOI

In-Process Verification / Inspection: X-Ray

Kitting

Moisture Sensitive Components and Materials

Secondary Assembly: Bonding

Secondary Assembly: Jumper Wire Installation

Secondary Assembly: Mechanical Part Installation

Secondary Assembly: Stranded Wire Tinning

Secondary Assembly: Wire Cutting & Stripping

##### **AC7120/2 - General Soldering of Printed Board Assemblies (to be used on audits on/after 9 April 2017)**

Build Through / Build Short

Electronic Component Preparation for Preassembly Process

Gold Removal

Hand Soldering

Part Placement: Clinched Component Leads

Part Placement: Manual

##### **AC7120/3 - Plated Through Hole Technology (requires AC7120/2) (to be used on audits on/after 9 April 2017)**

Wave Soldering

##### **AC7120/4 Rev A - Surface Mount Technology (requires AC7120/2) (to be used on audits**

**on/after 3 March 2019)**

Preparation

Solder Paste Printing: Stencil Printing

**AC7120/7 Rev A - Conformal Coating of Printed Board Assemblies (to be used on audits on/AFTER 05-Nov-2023)**

Conformal Coating of Printed Board Assemblies

**AC7120/8 - Encapsulation (to be used on audits on/after 9 April 2017)**

**AC7120/9 - Programming (to be used on audits on/after 9 April 2017)**

Programming

**AC7120/10 - Final Testing (to be used on audits on/after 9 April 2017)**

Final Testing

**AC7120/12 - Nadcap Audit Criteria for Depaneling (to be used on audits on/after 30 June 2019)**

Finishing of cut edges (Rotary, Guillotine, hand cut methods must answer this section)

Hand Cutters

Pizza Cutter ('V' Groove Depanelizer)